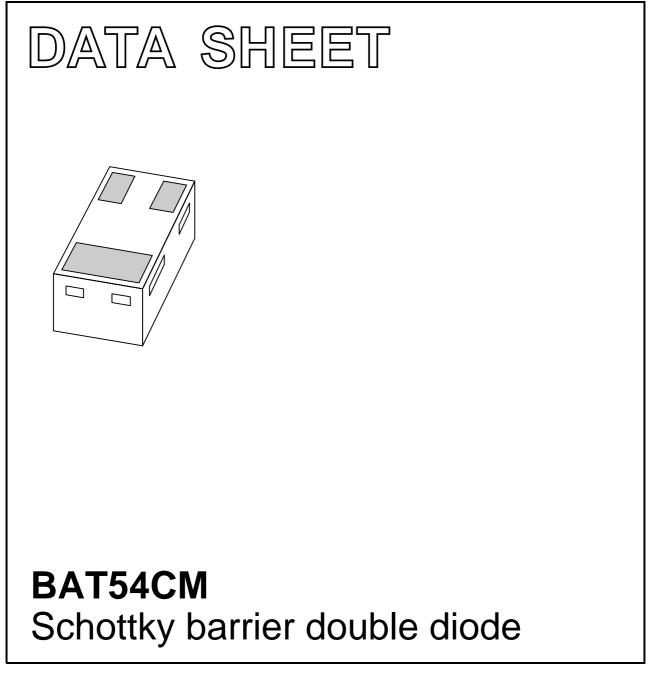
DISCRETE SEMICONDUCTORS



Product data sheet

2003 Nov 11



FEATURES

- Low forward voltage
- Leadless ultra small plastic package $(1.0 \times 0.6 \times 0.5 \text{ mm})$
- Boardspace 1.17 mm² (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

APPLICATIONS

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Mobile communications, digital (still) cameras, PDAs and PCMCIA cards.

DESCRIPTION

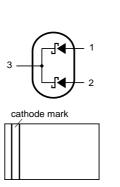
Planar Schottky barrier double diode encapsulated in a SOT883 leadless ultra small plastic package.

MARKING

TYPE NUMBER	MARKING CODE	
BAT54CM	S3	

PINNING

PIN	DESCRIPTION	
1	anode (a ₁)	
2	anode (a ₂)	
3	common cathode	



Top view

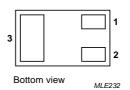


Fig.1 Simplified outline (SOT883) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
ITFE NOWBER	NAME	DESCRIPTION	VERSION
BAT54CM	_	leadless ultra small plastic package; 3 solder lands; body 1.0 \times 0.6 \times 0.5 mm	SOT883

BAT54CM

BAT54CM

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		-	30	V
I _F	continuous forward current		_	200	mA
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ s}; \delta \le 0.5$	_	300	mA
I _{FSM}	non-repetitive peak forward current	t _p < 10 ms	_	600	mA
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
P _{tot}	total power dissipation (per package)	$T_{amb} \le 25 \ ^{\circ}C$; note 1	_	250	mW

Note

1. Refer to SOT883 standard mounting conditions (footprint); FR4 with 60 μm copper strip line.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Refer to SOT883 standard mounting conditions (footprint), FR4 with 60 µm copper strip line.

Soldering

Reflow soldering is the only recommended soldering method.

ELECTRICAL CHARACTERISTICS

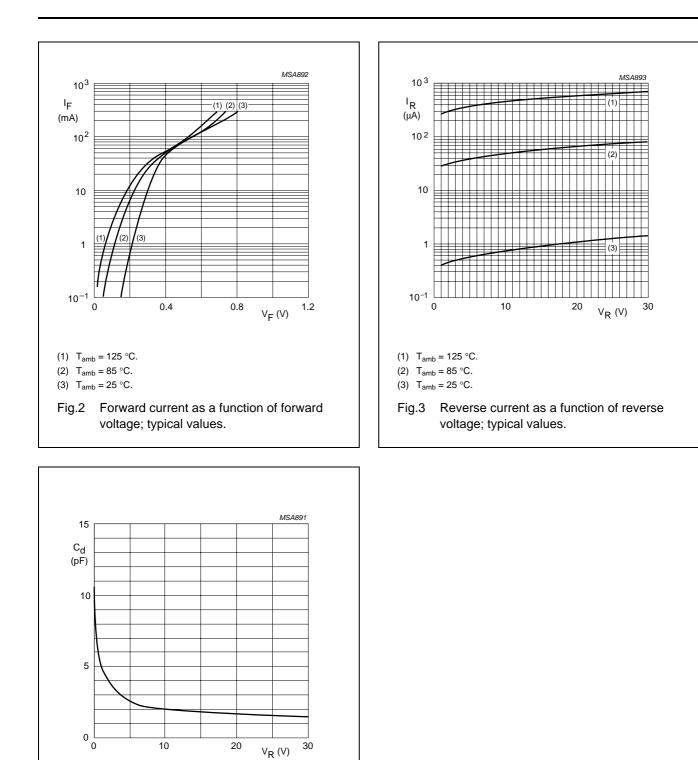
 $T_{amb} = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
Per diode				
V _F	forward voltage	see Fig.2;		
		I _F = 0.1 mA	240	mV
		I _F = 1 mA	320	mV
		I _F = 10 mA	400	mV
		I _F = 30 mA	500	mV
		I _F = 100 mA	800	mV
I _R	continuous reverse current	V _R = 25 V; note 1; see Fig.3	2	μA
C _d	diode capacitance	$f = 1 \text{ MHz}; V_R = 1 \text{ V}; \text{ see Fig.4}$	10	pF

Note

1. Pulsed test: $t_p \le 300 \ \mu s; \ \delta \le 0.02$.

BAT54CM

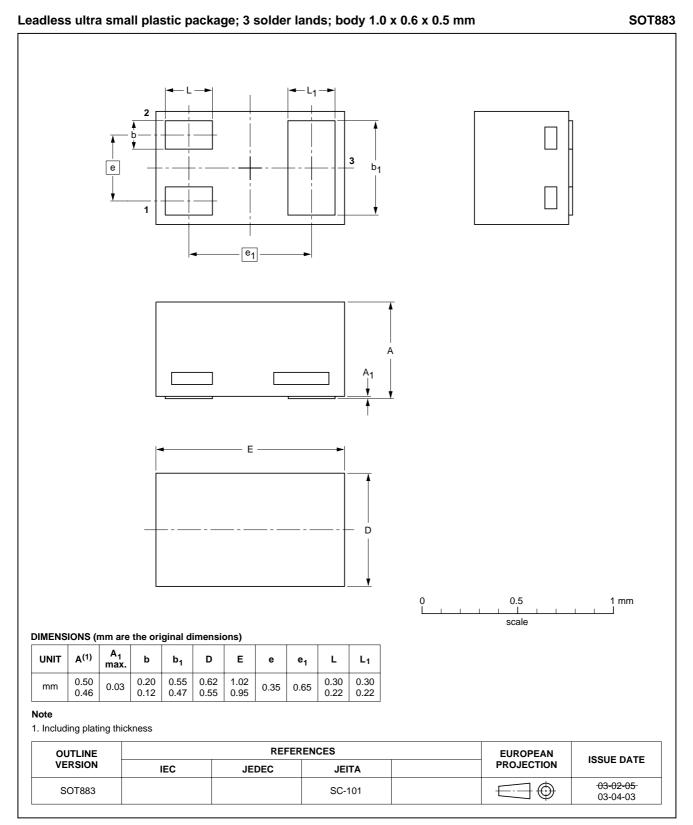


f = 1 MHz; T_{amb} = 25 °C.

Fig.4 Diode capacitance as a function of reverse voltage; typical values.

BAT54CM

PACKAGE OUTLINE



BAT54CM

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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This data sheet was changed to reflect the new company name NXP Semiconductors. No changes were made to the content, except for the legal definitions and disclaimers.

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401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

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- Skype ameyasales1 ameyasales2

> Customer Service :

Email service@ameya360.com

> Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com